



Description

The **PlasmaPro® Estrelas100** is a plasma etch tool with semi-automatic loading system. The tool is primarily configured to carry out etching of silicon, with size up to 100mm (4") diameter. A precise flow of one or more process gases is supplied to the chamber from a gas pod, then the tool uses RF power to create a plasma inside the chamber. The reactive ionic species generated within the plasma are guided onto the front surface of the wafers.

Specifications / Capabilities

Wafer size : Up to 4in Dia wafer

Maximal RF power is limited to 300 W and ICP power 5kW.

Etch materials : Si

Gases

C4F8,SF6,Ar,O2

Link

<https://www.oxinst.com/>

<https://plasma.oxinst.com/>